



Volume 12, Issue 1



#### **From the Director's Desk**

James Amano, Senior Director

#### ***Building on the Foundation***

For nearly 45 years, the SEMI Standards Program has played an important role in the sustained growth of the global semiconductor industry, developing over 970 documents, covering topics such as silicon wafers, equipment communication, physical interfaces, and EHS. [Read More](#)

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#### **Generic Counter Model**

Standardized "counter" information will help detect problems in advance. [Read More](#)

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#### **SCIS update**

SCIS activities are focused on establishing a baseline for measuring defects introduced by critical components. [Read More](#)

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#### **SEMICON Japan 2016 Highlights**

Standards meetings and related events at SEMICON Japan 2016 attracted over 320 participants. [Read More](#)

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#### **Bonded Wafers for 3D Integration**

3D stacking is enabled by wafer bonding, where two or more wafers are bonded into a single device. [Read More](#)

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#### **S2 Delayed Revisions related to Chemical Exposure**

This clarification will benefit the semiconductor industry by providing consistent and updated chemical conformance criteria. [Read More](#)

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#### **Major Revision to SEMI F30**

An updated standard to ensure alignment of purifier performance metrics and semiconductor fab requirements. [Read More](#)

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## GEM 300A

Smart Manufacturing requires security, traceability, visibility, and controllability. [Read More](#)

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## Standards Calendar

April 3-6 [North America Standards Spring Meetings](#)

[Click here for all Standards events.](#)

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